

## Electronic Acknowledgement Receipt

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<b>International Application Number:</b>	
<b>Confirmation Number:</b>	5987
<b>Title of Invention:</b>	EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT
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Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
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1	Transmittal Letter	09-12-02_IDS_with_foreign_certificate_after_Allowance.pdf	58095 aa8e8f2d24f08ea26d9d4125771eb2a6853c341b	no	2
<b>Warnings:</b>					
<b>Information:</b>					
2	Information Disclosure Statement (IDS) Filed (SB/08)	09-12-02_Form_PTO_SB08a.pdf	608407 b0eaedc61c55495f8446d1758b4ef77d194c873d	no	4
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3	NPL Documents	NP01_Japanese_Office_Action_JP2005516103.pdf	214051 5fdd066a800c66ca368083e3d1fb5da03a435c34	no	5
<b>Warnings:</b>					
<b>Information:</b>					
4	Fee Worksheet (PTO-875)	fee-info.pdf	30858 76da0ef1ab2ea1f97c5e7e61af4d61c59559b03	no	2
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